

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

DFN 2mm X 3mm Exp. Pad

(printed on: 2020-07-11 19:31:47)

**TOTAL MASS (g) : 0.01493**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000775	1000000	51907.71875		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.005723	975000	383313.34375		
		Iron (Fe)	7439-89-6	0.000141	24000	9443.85449219		
		Phosphorus (P)	7723-14-0	0.000002	300	133.955383301		
		Zinc (Zn)	7440-66-6	0.000004	700	267.910766602		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.005870</b>	<b>1000000</b>	<b>393159.09375</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000260	1000000	17437.140625		
		<b>External Plating Total:</b>				<b>0.000260</b>	<b>1000000</b>	<b>17437.140625</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000136	1000000	9108.96679688		
<b>Internal Plating Total:</b>				<b>0.000136</b>	<b>1000000</b>	<b>9108.96679688</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000198	800000	13261.5839844		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000049	200000	3281.90698242		
<b>Die Attach Total:</b>				<b>0.000247</b>	<b>1000000</b>	<b>16543.4902344</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.000989	130000	66240.9375		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.006545	860000	438369		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000076	10000	5090.3046875		
		<b>Encapsulation Total:</b>				<b>0.007610</b>	<b>1000000</b>	<b>509700.3125</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000032	1000000	2143.28613281		
					<b>TOTAL MASS (g) :</b>	<b>0.01493</b>		